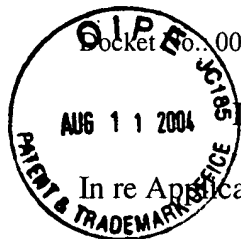


JFW



Docket No. 008063 USA MTCG/PINTGR

PATENT/OFFICIAL

AUG 11 2004

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Deenesh PADHI et al.

Serial No. 10/812,480

Filed: March 30, 2004

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: Group Art Unit:
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: Examiner:

For: SELECTIVE METAL ENCAPSULATION SCHEMES

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Honorable Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In accordance with the provisions of 37 C.F.R. 1.56, 1.97 and 1.98, the attention of the Patent and Trademark Office is hereby directed to the documents listed on the attached form PTO-1449. It is respectfully requested that the documents be expressly considered during the prosecution of this application, and that the documents be made of record therein and appear among the "References Cited" on any patent to issue therefrom. Copies of any cited U.S. Patents and U.S. Patent Publications are not being submitted in accordance with 37 CFR 1.98(a)(2)(i).

This Information Disclosure Statement is being filed within three months of the U.S. filing date OR before the mailing date of a first Office Action on the merits. No certification or fee is required.

In accordance with 37 C.F.R. § 1.97(g) and (h), the filing of this IDS should not be construed as a representation that a search had been made or that information cited is, or is considered to be, material to patentability as defined in 37 C.F.R. § 1.56 (b), or that any cited document listed or attached is (or constitutes) prior art. Unless otherwise indicated, the date of

Serial No. 10/812,480

publication indicated for an item is taken from the face of the item, and Applicant reserves the right to prove that the date of publication is in fact different.

No fee is believed to be required; however, the Commissioner is authorized to charge any deficiency in any fees pursuant to 37 CFR § 1.17 associated with this communication and to credit any excess payment to Deposit Account No. 08-0219.

Respectfully submitted,

WILMER CUTLER PICKERING HALE AND DORR LLP



Scott M. Alter


Registration No. 32,879

1455 Pennsylvania Avenue, NW
Washington, DC 20004

TEL 202.942.8428 SMA/lrm

FAX 202.942.8484

Date: 8/11/04

INFORMATION DISCLOSURE CITATION IN AN APPLICATION (PTO-1449)				ATTY. DOCKET NO. 008063 USA MTCG/PINTGR		SERIAL NO. 10/812,480	
				APPLICANT Deenesh PADHI et al.			
				FILING DATE March 30, 2004		GROUP	
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EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to Applicant.

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